



**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**In re Application of:** Nishant Sinha

**Serial No.:** 10/668,914

**Filed:** September 23, 2003

**For:** PROCESS AND INTEGRATION  
SCHEME FOR FABRICATING  
CONDUCTIVE COMPONENTS,  
THROUGH-VIAS AND  
SEMICONDUCTOR COMPONENTS  
INCLUDING CONDUCTIVE THROUGH-  
WAFER VIAS

**Confirmation No.:** 2525

**Examiner:** W. Lindsay Jr.

**Group Art Unit:** 2812

**Attorney Docket No.:** 2269-5859US  
(02-0390.00/US)

**CERTIFICATE OF MAILING**

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

September 20, 2005  
Date

Signature

Erika Gandre  
Name (Type/Print)

**AMENDMENT**

Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Examiner:

This Amendment is being filed in response to the Office Action mailed on May 20, 2005, the three month shortened statutory period for response to which expired on August 20, 2005.

This Amendment is being filed with a petition for a one month extension of time and the appropriate fee.

**Amendments to the claims** appear in the listing of the claims that begins on page 2 of this paper; and

**Remarks** start at page 5 of this paper.